National Semiconductor

December 1994

54F/74F827 • 74F828
10-Bit Buffers/Line Drivers

General Description

The ’F827 and ’F828 10-bit bus buffers provide high performance bus interface buffering for wide data/address paths or buses carrying parity. The 10-bit buffers have NOR output enables for maximum control flexibility.

The ’F827 and ’F828 are functionally- and pin-compatible to AMD’s Am29827 and Am29828. The ’F828 is an inverting version of the ’F827.

Features

- TRI-STATE® output
- ’F828 is inverting
- Direct replacement for AMD’s Am29827 and Am29828

Commercial	Military	Package Number	Package Description
74F827SPC		N24C	24-Lead (0.300″ Wide) Molded Dual-In-Line
	54F827SDM (Note 2)	J24F	24-Lead (0.300″ Wide) Ceramic Dual-In-Line
74F827SC (Note 1)		M24B	24-Lead (0.300″ Wide) Molded Small Outline, JEDEC
	54F827FM (Note 2)	W24C	24-Lead Cerpack
	54F827LM (Note 2)	E28A	24-Lead Ceramic Leadless Chip Carrier, Type C
74F828SPC		N24C	24-Lead (0.300″ Wide) Molded Dual-In-Line
74F828SC (Note 1)		M24B	24-Lead (0.300″ Wide) Molded Small Outline, JEDEC

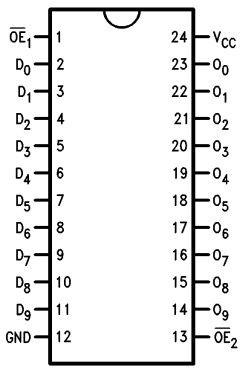
Note 1: Devices also available in 13″ reel. Use suffix = SCX.

Note 2: Military grade device with environmental and burn-in processing. Use suffix = SDMQB, FMQB and LMQB.

Connection Diagrams

Pin Assignment for DIP, Flatpak and SOIC

’F827



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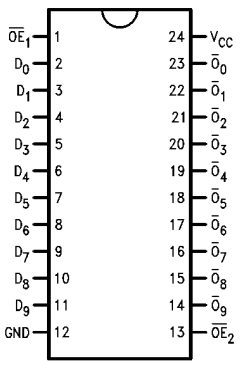
’F828



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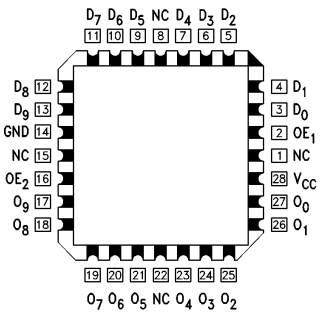
Pin Assignment for LCC

’F827



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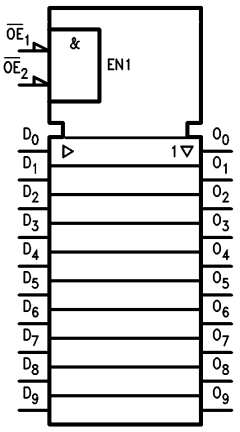
Logic Symbols

IEEE/IEC
'F827



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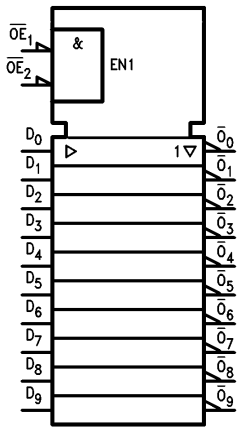
IEEE/IEC
'F828



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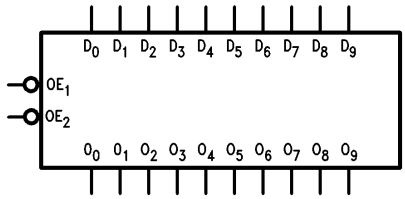
'F827



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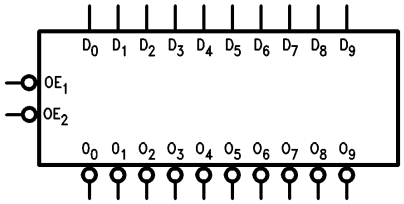
'F828



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Unit Loading/Fan Out

Pin Names	Description	54F/74F	
		U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
$\overline{OE}_1$, $\overline{OE}_2$	Output Enable Input	1.0/1.0	20 μA/ $-$0.6 mA
D_0-D_7	Data Inputs	1.0/1.0	20 μA/ $-$0.6 mA
O_0-O_7	Data Outputs, TRI-STATE	600/106.6 (80)	$-$12 mA/64 mA (48 mA)

Functional Description

The 'F827 and 'F828 are line drivers designed to be employed as memory address drivers, clock drivers and bus-oriented transmitters/receivers which provide improved PC board density. The devices have TRI-STATE outputs controlled by the Output Enable ($\overline{OE}$) pins. The outputs can sink 64 mA (48 mA mil) and source 15 mA. Input clamp diodes limit high-speed termination effects.

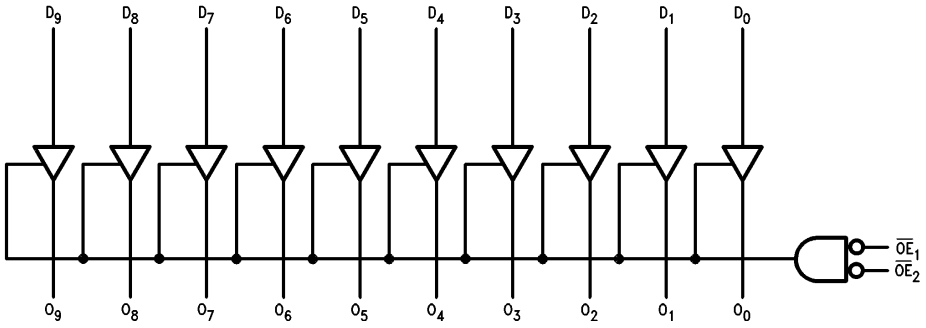
Function Table

Inputs		Outputs		Function
$\overline{OE}$	D_n	O_n		
		'F827	'F828	
L	H	H	L	Transparent
L	L	L	H	Transparent
H	X	Z	Z	High Z

H = HIGH Voltage level
L = LOW Voltage Level
Z = High Impedance
X = Immaterial

Logic Diagrams

'F827



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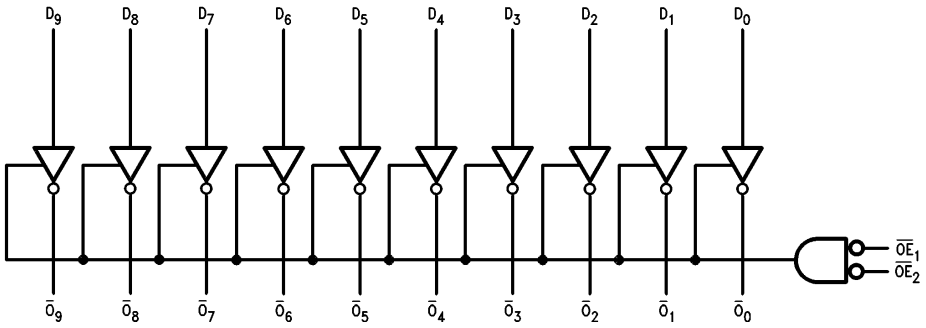
Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

'F828



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Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +175°C
Plastic	−55°C to +150°C
V_{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V_{CC} = 0V)	
Standard Output	−0.5V to V_{CC}
TRI-STATE Output	−0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I_{OL} (mA)

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

Free Air Ambient Temperature	
Military	−55°C to +125°C
Commercial	0°C to +70°C
Supply Voltage	
Military	+4.5V to +5.5V
Commercial	+4.5V to +5.5V

DC Electrical Characteristics

Symbol	Parameter		54F/74F Min	54F/74F Typ	54F/74F Max	Units	V_{CC}	Conditions
V_{IH}	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal
V_{IL}	Input LOW Voltage				0.8	V		Recognized as a LOW Signal
V_{CD}	Input Clamp Diode Voltage				−1.2	V	Min	I_{IN} = −18 mA
V_{OH}	Output HIGH Voltage	54F 10% V_{CC}	2.4			V	Min	I_{OH} = −3 mA
		54F 10% V_{CC}	2.0					I_{OH} = −12 mA
		74F 10% V_{CC}	2.4					I_{OH} = −3 mA
		74F 10% V_{CC}	2.0					I_{OH} = −15 mA
		74F 5% V_{CC}	2.7					I_{OH} = −3 mA
V_{OL}	Output LOW Voltage	54F 10% V_{CC}			0.55	V	Min	I_{OL} = 48 mA
		74F 10% V_{CC}			0.55			I_{OL} = 64 mA
I_{IH}	Input HIGH Current	54F			20.0	μA	Max	V_{IN} = 2.7V
		74F			5.0			
I_{BVI}	Input HIGH Current Breakdown Test	54F			100	μA	Max	V_{IN} = 7.0V
		74F			7.0			
I_{CEX}	Output HIGH Leakage Current	54F			250	μA	Max	V_{OUT} = V_{CC}
		74F			50			
V_{ID}	Input Leakage Test	74F	4.75			V	0.0	I_{ID} = 1.9 μA All Other Pins Grounded
I_{OD}	Output Leakage Circuit Current	74F			3.75	μA	0.0	V_{IOD} = 150 mV All Other Pins Grounded
I_{IL}	Input LOW Current				−0.6	mA	Max	V_{IN} = 0.5V
I_{OZH}	Output Leakage Current				50	μA	Max	V_{OUT} = 2.7V
I_{OZL}	Output Leakage Current				−50	μA	Max	V_{OUT} = 0.5V
I_{OS}	Output Short-Circuit Current		−100		−225	mA	Max	V_{OUT} = 0V

DC Electrical Characteristics (Continued)

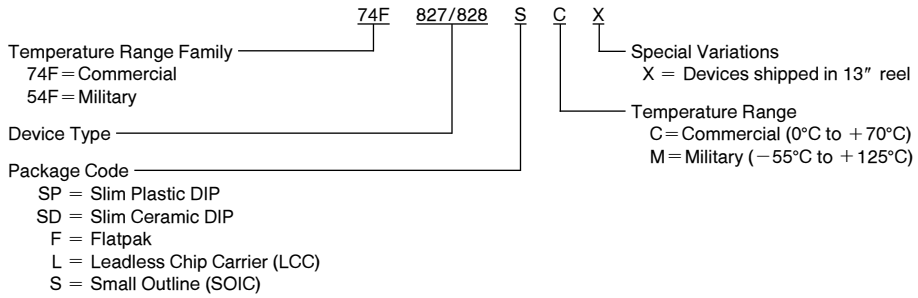
Symbol	Parameter	54F/74F			Units	V_{CC}	Conditions
		Min	Typ	Max			
I_{ZZ}	Bus Drainage Test			500	μA	0.0V	V_{OUT} = 5.25V
I_{CCH}	Power Supply Current ('F827)		30	45	mA	Max	V_O = HIGH
I_{CCL}	Power Supply Current ('F827)		60	90	mA	Max	V_O = LOW
I_{CCZ}	Power Supply Current ('F827)		40	60	mA	Max	V_O = HIGH Z
I_{CCH}	Power Supply Current ('F828)		14	20	mA	Max	V_O = HIGH
I_{CCL}	Power Supply Current ('F828)		56	85	mA	Max	V_O = LOW
I_{CCZ}	Power Supply Current ('F828)		35	50	mA	Max	V_O = HIGH Z

AC Electrical Characteristics

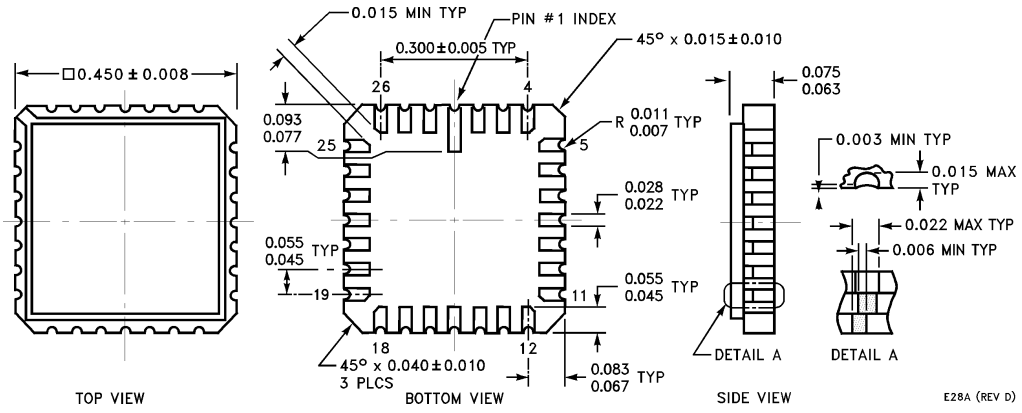
Symbol	Parameter	74F T_A = +25°C, V_{CC} = +5.0V, C_L = 50 pF			54F T_A, V_{CC} = Mil, C_L = 50 pF		74F T_A, V_{CC} = Com, C_L = 50 pF		Units
		Min	Typ	Max	Min	Max	Min	Max	
t_{PLH}	Propagation Delay	1.0	3.0	5.5	1.0	7.5	1.0	6.5	ns
t_{PHL}	Data to Output ('F827)	1.5	3.3	5.5	1.5	7.0	1.5	6.0	
t_{PLH}	Propagation Delay	1.0	3.0	5.0			1.0	5.5	ns
t_{PHL}	Data to Output ('F828)	1.0	2.0	4.0			1.0	4.0	
t_{PZH}	Output Enable Time	3.0	5.7	9.0	2.5	10.0	2.5	9.5	ns
t_{PZL}	$\overline{OE}$ to O_n	3.5	6.8	11.5	3.0	12.5	3.0	12.0	
t_{PHZ}	Output Disable Time	1.5	3.3	8.0	1.5	9.0	1.5	8.5	ns
t_{PLZ}	$\overline{OE}$ to O_n	1.0	3.5	8.0	1.0	9.0	1.0	8.5	

Ordering Information

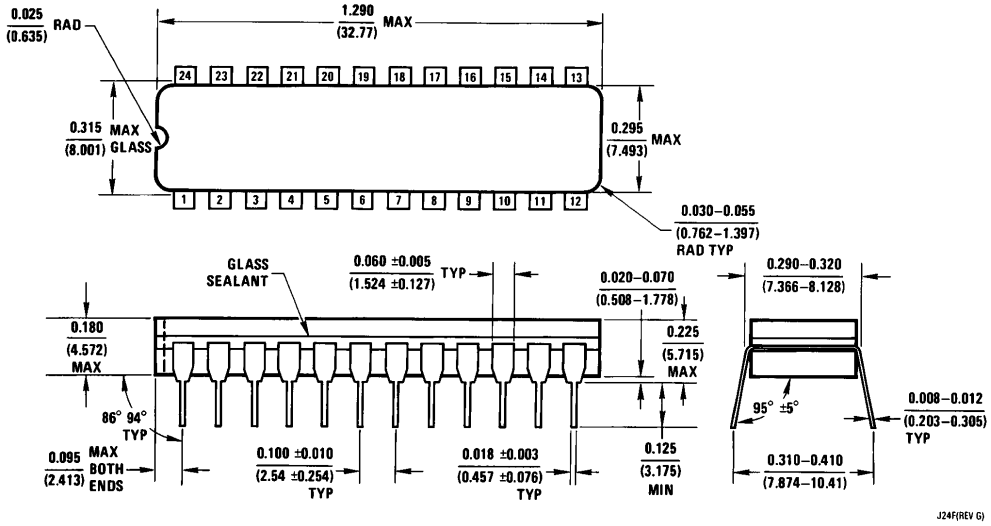
The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:



Physical Dimensions inches (millimeters)

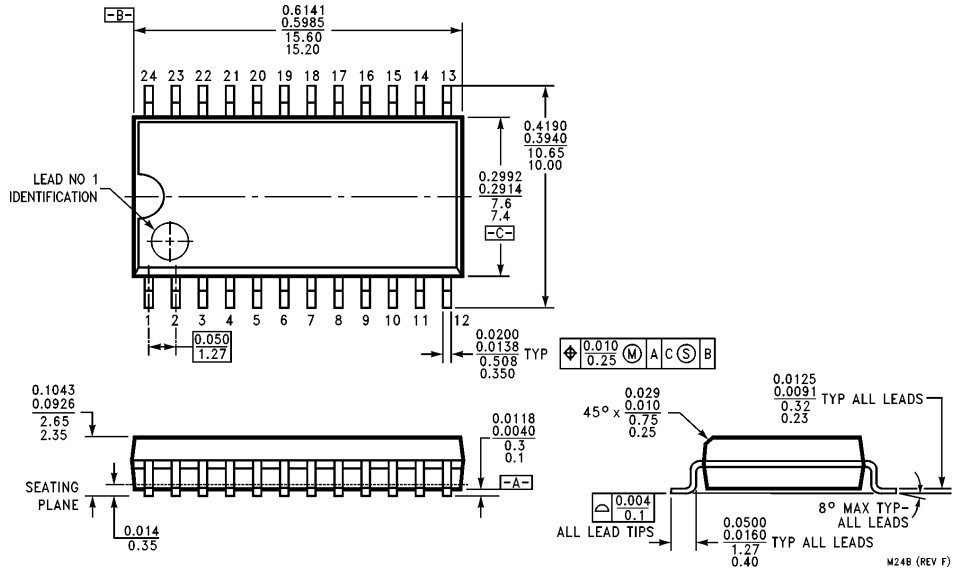


28-Lead Ceramic Leadless Chip Carrier (L)
NS Package Number E28A

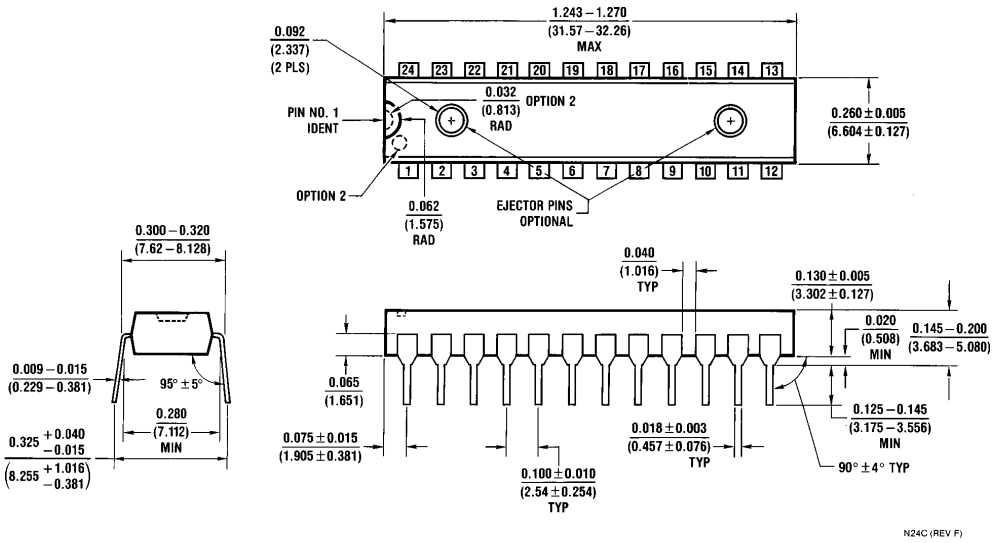


24-Lead (0.300″ Wide) Ceramic Dual-In-Line Package (SD)
NS Package Number J24F

Physical Dimensions inches (millimeters) (Continued)

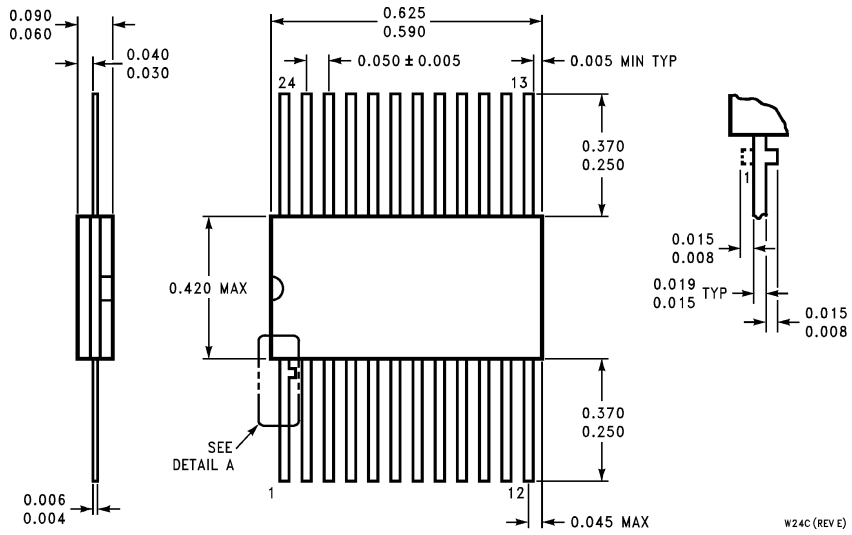


24-Lead Small Outline Integrated Circuit (S)
NS Package Number M24B



24-Lead Plastic Slim (0.300″ Wide) Dual-In-Line Package (SP)
NS Package Number N24C

Physical Dimensions inches (millimeters) (Continued)



24-Lead Ceramic Flatpak (F)
NS Package Number W24C

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